

L Number	Hits	Search Text	DB	Time stamp
-	1	carpenter.in. and drennan.in. and easton.in. and grant.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 13:51
-	1	carpenter.in. and drennan.in. easton.in. and grant.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 08:11
-	52	cryogenic near3 cleaning and liquid near12 nitrogen	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 13:52
-	1	"0661873".PN.	USPAT	2003/04/24 08:19
-	1	"1191451".PN.	USPAT	2003/04/24 08:20
-	1	"1978204".PN.	USPAT	2003/04/24 08:20
-	1	"1978204".PN.	USPAT	2003/04/24 08:21
-	1	"2259644".PN.	USPAT	2003/04/24 08:21
-	1	"2347464".PN.	USPAT	2003/04/24 08:21
-	1	"2402967".PN.	USPAT	2003/04/24 08:21
-	1	"2854360".PN.	USPAT	2003/04/24 08:21
-	1	"3182669".PN.	USPAT	2003/04/24 08:21
-	1	"3419427".PN.	USPAT	2003/04/24 08:21
-	1	"3436263".PN.	USPAT	2003/04/24 08:21
-	1	"3453221".PN.	USPAT	2003/04/24 08:21
-	1	"3527414".PN.	USPAT	2003/04/24 08:21
-	1	"3536529".PN.	USPAT	2003/04/24 08:21
-	1	"3614873".PN.	USPAT	2003/04/24 08:21
-	1	"3741804".PN.	USPAT	2003/04/24 08:21
-	1	"3745125".PN.	USPAT	2003/04/24 08:21
-	1	"3746023".PN.	USPAT	2003/04/24 08:21
-	1	"3774855".PN.	USPAT	2003/04/24 08:21
-	1	"3785575".PN.	USPAT	2003/04/24 08:21
-	1	"3856667".PN.	USPAT	2003/04/24 08:21
-	1	"3914132".PN.	USPAT	2003/04/24 08:21
-	1	"3995816".PN.	USPAT	2003/04/24 08:22
-	1	"4011159".PN.	USPAT	2003/04/24 08:22
-	1	"4025990".PN.	USPAT	2003/04/24 08:22
-	1	"4043140".PN.	USPAT	2003/04/24 08:22
-	1	"4102503".PN.	USPAT	2003/04/24 08:22
-	1	"4157016".PN.	USPAT	2003/04/24 08:22
-	1	"4157016".PN.	USPAT	2003/04/24 08:42
-	0	cryogenic near3 cleaning and layer and seperate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 08:45
-	24	cryogenic near3 cleaning and layer and separate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 08:48
-	88	sacrificial near3 coating and clean\$3 and separate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:02
-	1	"3676455".PN.	USPAT	2003/04/24 08:52
-	1	"3839066".PN.	USPAT	2003/04/24 08:53
-	1	"4141755".PN.	USPAT	2003/04/24 08:53
-	1	"4169088".PN.	USPAT	2003/04/24 08:53
-	1	"4177099".PN.	USPAT	2003/04/24 08:53
-	1	"4199620".PN.	USPAT	2003/04/24 08:53
-	1	"4241141".PN.	USPAT	2003/04/24 08:53
-	1	"4322508".PN.	USPAT	2003/04/24 08:53
-	1	"4337299".PN.	USPAT	2003/04/24 08:53
-	1	"4349586".PN.	USPAT	2003/04/24 08:53
-	1	"4353745".PN.	USPAT	2003/04/24 08:53
-	1	"4412033".PN.	USPAT	2003/04/24 08:53

-	1	"4428994".PN.	USPAT	2003/04/24 08:53
-	1	"4463038".PN.	USPAT	2003/04/24 08:53
-	1	"4499149".PN.	USPAT	2003/04/24 08:53
-	1	"4590097".PN.	USPAT	2003/04/24 08:53
-	1	"4600522".PN.	USPAT	2003/04/24 08:53
-	1	"4716056".PN.	USPAT	2003/04/24 08:53
-	1	"4758622".PN.	USPAT	2003/04/24 08:53
-	1	"4777090".PN.	USPAT	2003/04/24 08:53
-	1	"4859791".PN.	USPAT	2003/04/24 08:53
-	1	"4943680".PN.	USPAT	2003/04/24 08:53
-	1	"5017237".PN.	USPAT	2003/04/24 08:53
-	1	"5024780".PN.	USPAT	2003/04/24 08:53
-	1	"5039745".PN.	USPAT	2003/04/24 08:53
-	1	"5049314".PN.	USPAT	2003/04/24 08:53
-	1	"5061518".PN.	USPAT	2003/04/24 08:54
-	1	"5084370".PN.	USPAT	2003/04/24 08:54
-	1	"5177154".PN.	USPAT	2003/04/24 08:54
-	1	"5330788".PN.	USPAT	2003/04/24 08:54
-	1	"5352733".PN.	USPAT	2003/04/24 08:54
-	1	"5387434".PN.	USPAT	2003/04/24 08:54
-	1	"5418006".PN.	USPAT	2003/04/24 08:54
-	1	"5496642".PN.	USPAT	2003/04/24 08:54
-	1	"5631042".PN.	USPAT	2003/04/24 08:54
-	2	sacrificial near3 coating and sonic and (semiconductor wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:05
-	6	sacrificial near3 coating and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/16 13:53
-	0	sacrificial near3 coating near22 freez\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:10
-	0	sacrificial near3 coat\$3g near22 freez\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:11
-	19	sacrificial near3 coat\$3g and freez\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:12
-	42	clean\$3 and freez\$3 and sonic and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:16
-	12	peel\$3 near12 adhesive near22 (contaminant foreign near3 matter) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:21
-	3206	particle near3 removal and (adhesive adhere adherent)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:23
-	252	particle near3 removal and (adhesive adhere adherent) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/24 09:24
-	1	"3080263".PN.	USPAT	2003/04/24 09:30
-	1	"3717897".PN.	USPAT	2003/04/24 09:30
-	1	"3754991".PN.	USPAT	2003/04/24 09:30
-	1	"4156619".PN.	USPAT	2003/04/24 09:30

-	1	"5320706".PN.	USPAT	2003/04/24 09:30
-	86035	polymer and adhesive and (heat energy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 09:40
-	198	polymer and adhesive and (heat energy) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 10:39
-	26	polymer and adhesive and (heat energy) and 134/\$.ccls. and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 10:39
-	36130	adhesive and curable polymer\$3 and clean\$3 and (wafer semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 12:58
-	27984	adhesive and curable polymer\$3 and clean\$3 near22 (wafer semiconductor) and 234/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 12:59
-	0	adhesive and curable near2 polymer\$3 and clean\$3 near22 (wafer semiconductor) and 234/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 12:59
-	1	adhesive and curable near2 polymer\$3 and clean\$3 near22 (wafer semiconductor) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 13:02
-	50	adhesive and curable near2 polymer\$3 and clean\$3 near22 (wafer semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/25 13:04
-	1	"3080263".PN.	USPAT	2003/04/26 06:57
-	1	"3717897".PN.	USPAT	2003/04/26 06:57
-	1	"3754991".PN.	USPAT	2003/04/26 07:00
-	1	"4156619".PN.	USPAT	2003/04/26 07:00
-	1	"5320706".PN.	USPAT	2003/04/26 07:00
-	0	semiconductor near3 wafer and ultrasonic near3 clean\$3 and water	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 07:20
-	0	semiconductor near3 wafer and ultrasonic near3 clean\$3 and water and 134/1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 07:21
-	48	semiconductor near3 wafer and ultrasonic near3 clean\$3 and water and 134/1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 07:21
-	38	semiconductor near3 wafer and ultrasonic near3 clean\$3 and water and 134/1.ccls.	USPAT	2003/04/26 07:51
-	1	134/\$.ccls. and curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:12

-	158	curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:13
-	1	curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive) and clean\$3.ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:13
-	1	curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive) and (removal clean\$3).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:14
-	130	curable near1 polymer and (wafer semiconductor) and coat\$3 and (contaminate clean\$3 adhere adhesive) and (adhesive removal clean\$3).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:23
-	361	curable near1 polymer and (face skin pore) and coat\$3 and (contaminate clean\$3 adhere adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:24
-	361	curable near1 polymer and (face skin pore) and coat\$3 and (contaminate clean\$3 adhere adhesive) and (adhesive removal clean\$3 skin face pore).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:30
-	0	curable near1 polymer and (face skin pore) and coat\$3 and (contaminate clean\$3 adhere adhesive) and (adhesive removal clean\$3 skin face pore).ti. and pore near2 cleaning	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:31
-	0	curable near1 polymer and pore near2 cleaning	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:31
-	84	pore near2 cleaning	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:44
-	2	pore near2 cleaning and (polyimide lacquer latex rubber near1 cement)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:47
-	3684	polyimide and adhesive and cleaning	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:47
-	3684	polyimide and adhesive and cleaning sacrificail and coating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:48
-	244	polyimide and adhesive and cleaning and sacrificial and coating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:48
-	244	polyimide and adhesive and cleaning and sacrificial and coating and surface	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:48

-	20	polyimide and adhesive and cleaning and sacrificial and coating and surface and curable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:49
-	18	polyimide and adhesive and cleaning and sacrificial and coating and surface and curable and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 08:49
-	1	"2495729".PN.	USPAT	2003/04/26 09:36
-	1	"3063873".PN.	USPAT	2003/04/26 09:36
-	1	"3079284".PN.	USPAT	2003/04/26 09:36
-	1	"3404134".PN.	USPAT	2003/04/26 09:36
-	1	"3634278".PN.	USPAT	2003/04/26 09:36
-	1	"4053666".PN.	USPAT	2003/04/26 09:36
-	2	"20020189635"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 09:50
-	38370	sonic near5 clean\$3 and dislodge near6 particulate matter and polymer and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:03
-	0	sonic near5 clean\$3 and dislodge near6 particulate near3 matter and polymer and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:03
-	0	sonic near5 clean\$3 and dislodge near6 (particulate matter) and polymer and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:03
-	68	sonic near5 clean\$3 and polymer and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:03
-	68	sonic near5 clean\$3 and polymer and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:27
-	31	(ultrasonic sonic) near5 clean\$3 and sacrificial near3 (coating layer polymer) and clean\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/26 10:28
-	2	5690749.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 09:39
-	1	"3080263".PN.	USPAT	2003/09/18 09:35
-	1	"3717897".PN.	USPAT	2003/09/18 09:37
-	1	"3754991".PN.	USPAT	2003/09/18 09:37
-	1	"4156619".PN.	USPAT	2003/09/18 09:37
-	1	"5320706".PN.	USPAT	2003/09/18 09:37
-	573	strippable near2 coating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 09:43
-	5	strippable near2 coating and (megasonic ultrasonic sonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/18 09:41

-	36	strippable near2 coating and contaminant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 09:43
-	56	strippable near2 (film coating) and contaminant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 10:50
-	2	ultrasonic near33 encapsulat\$4 near33 contaminant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 10:51
-	564	ultrasonic near33 encapsulat\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 10:51
-	2	ultrasonic near33 encapsulat\$4 and 134/.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 10:52
-	30	ultrasonic near33 encapsulat\$4 and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 10:54
-	302199	encapsulat\$4 contaminant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 10:55
-	10960	encapsulat\$4 and contaminant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 10:55
-	807	encapsulat\$4 with contaminant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 10:55
-	106	encapsulat\$4 with contaminant and (sonic ultrasonic megasonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 11:27
-	2	("4,178,188").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 11:27
-	1	"2009278".PN.	USPAT	2003/09/18 13:41
-	1	"4806277".PN.	USPAT	2003/09/18 13:41
-	1	"4476177".PN.	USPAT	2003/09/18 13:42
-	1	"5320706".PN.	USPAT	2003/09/18 13:45
-	375	(apply application) near122 film with heat\$3 with strip\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 14:17
-	57627	(apply application) near122 film with heat\$3 with strip\$4 an 134/.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 14:19

-	1	(apply application) near122 film with heat\$3 with strip\$4 and 134/.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 14:24
-	564	(134/4.ccls. 134/5.ccls. 134/10.ccls. 134/17.ccls.) and (contam\$6 particle) with remov\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 15:44
-	0	(134/4.ccls. 134/5.ccls. 134/10.ccls. 134/17.ccls.) and (contam\$6 particle) with abate\$4 and \$5sonic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 15:45
-	0	(134/4.ccls. 134/5.ccls. 134/10.ccls. 134/17.ccls.) and (contam\$6 particle) with abate\$4 and (ultrasonic sonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 15:45
-	6	(134/4.ccls. 134/5.ccls. 134/10.ccls. 134/17.ccls.) and (contam\$6 particle) and abate\$4 and (ultrasonic sonic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 15:45
-	13	134/4.ccls. and ultrasonic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/18 18:30
-	1	"2009278".PN.	USPAT	2003/09/18 18:24
-	1	"3166445".PN.	USPAT	2003/09/18 18:24
-	1	"3410724".PN.	USPAT	2003/09/18 18:24
-	1	"3419427".PN.	USPAT	2003/09/18 18:24
-	1	"3733710".PN.	USPAT	2003/09/18 18:24
-	1	"4186032".PN.	USPAT	2003/09/18 18:24
-	1	"4266982".PN.	USPAT	2003/09/18 18:24
-	1	"4409034".PN.	USPAT	2003/09/18 18:24
-	1	"4586962".PN.	USPAT	2003/09/18 18:24
-	1	"4622075".PN.	USPAT	2003/09/18 18:24
-	1	"4628616".PN.	USPAT	2003/09/18 18:24
-	1	"4806277".PN.	USPAT	2003/09/18 18:24
-	99	134/6.ccls. and ultrasonic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/16 13:52
-	2	carpenter.in. and drennan.in. and easton.in. and grant.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/16 13:51
-	2	carpenter.in. and drennan.in. easton.in. and grant.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/16 13:52
-	56	cryogenic near3 cleaning and liquid near12 nitrogen	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/16 13:52
-	107	134/6.ccls. and ultrasonic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/16 13:53
-	6	sacrificial near3 coating and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/01/16 13:53